

CLAIMS

What is claimed is:

1-24. (Canceled).

25. An encapsulation method for leadless semiconductor packages, the method comprising:

attaching a plurality of dice to die pads in a plurality of cavities of a lead frame, the cavities arranged in a matrix of columns and rows;

electrically connecting the dice to a plurality of conducting portions of the leadframe;

causing a molding material to flow into a first cavity;

causing said molding material to flow from said first cavity into a second cavity adjacent to and in the same column as said first cavity; and

causing said molding material to flow from said first cavity into a third cavity adjacent to and in the same row as said first cavity.

26. The encapsulation method of Claim 25, further comprising causing said molding material to flow from said first cavity into a fourth cavity adjacent to and in the same row as said first cavity.

27. The encapsulation method of Claim 25, further comprising:

causing said molding material to flow from said second cavity into a fourth cavity adjacent to and in the same column as said first cavity; and

causing said molding material to flow from said second cavity into a fifth cavity adjacent to and in the same row as said second cavity.